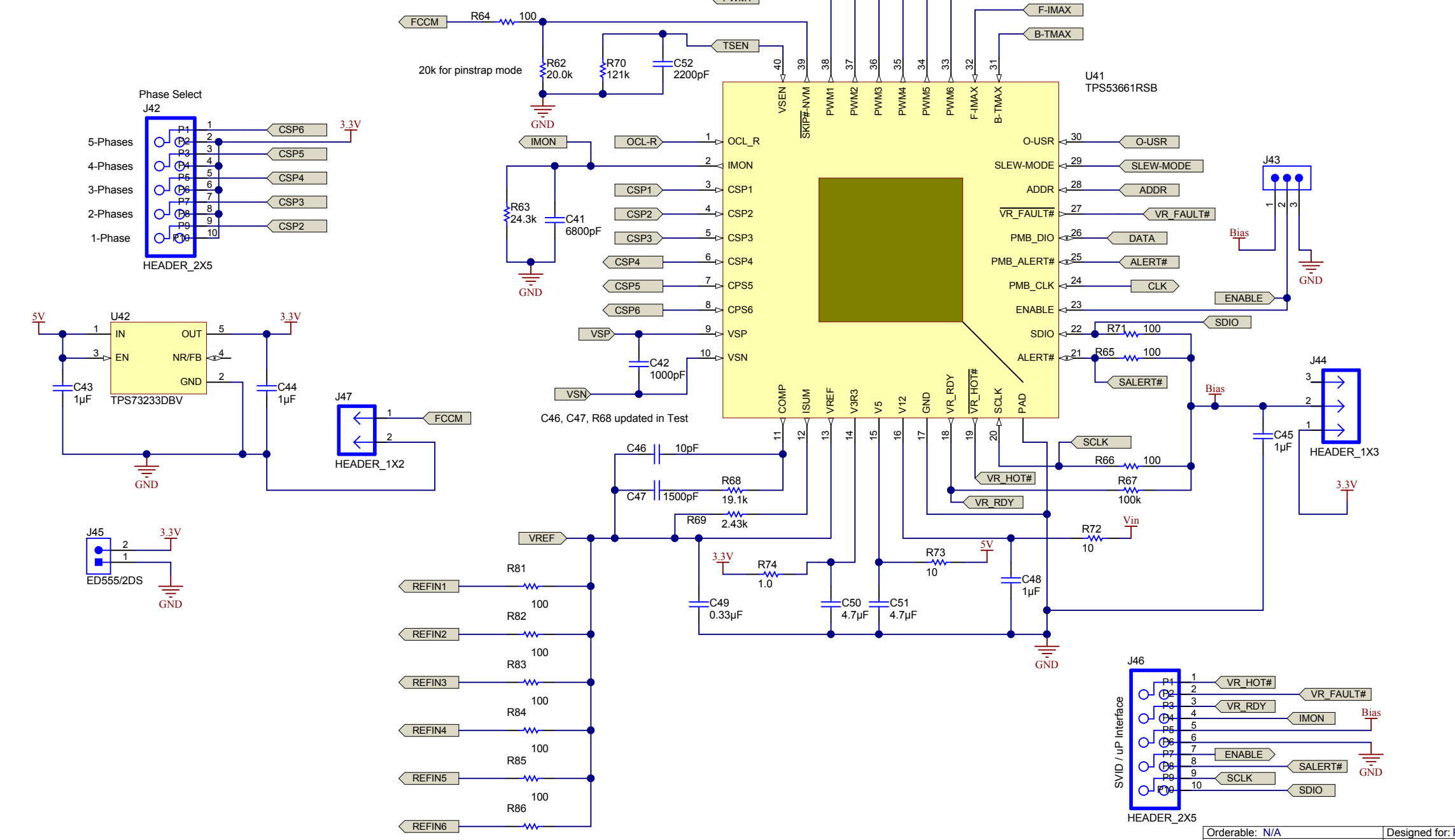


With Non Volatile Memory programming these 12 "bootstrap" resistors are not needed.

slew = 5mV/us, 1.52VID max, individual phase interleave when in 4 phases  
no turbo mode, no phase shedding, zero loadline

Remove R62 for Non Volatile Memory programming

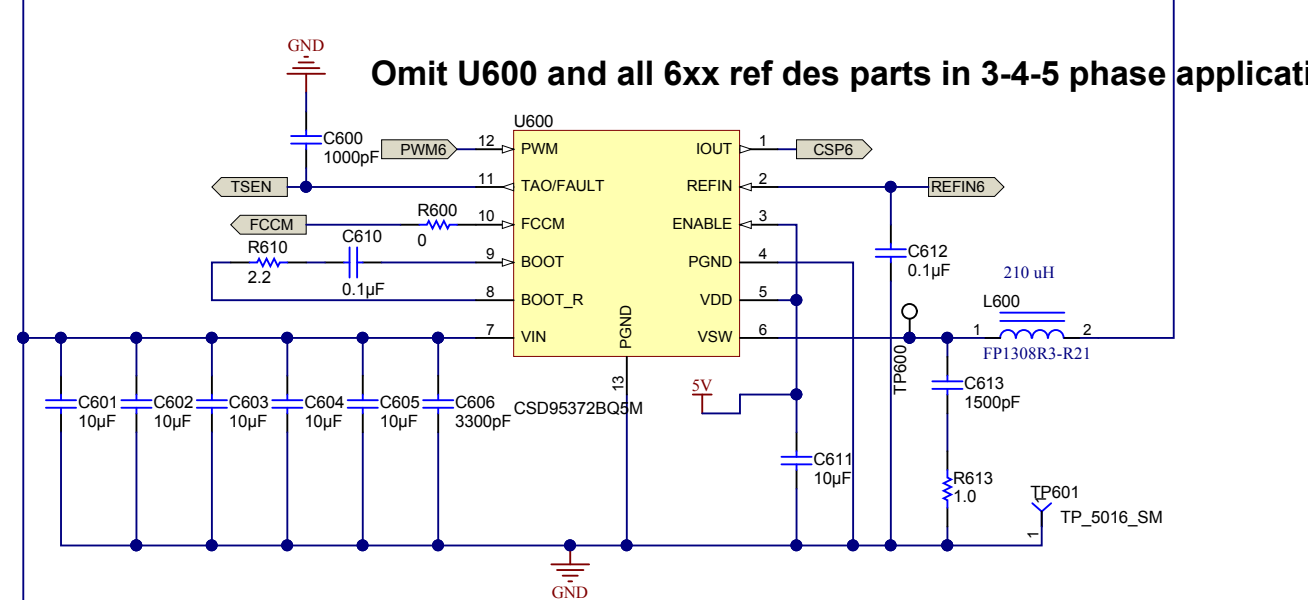
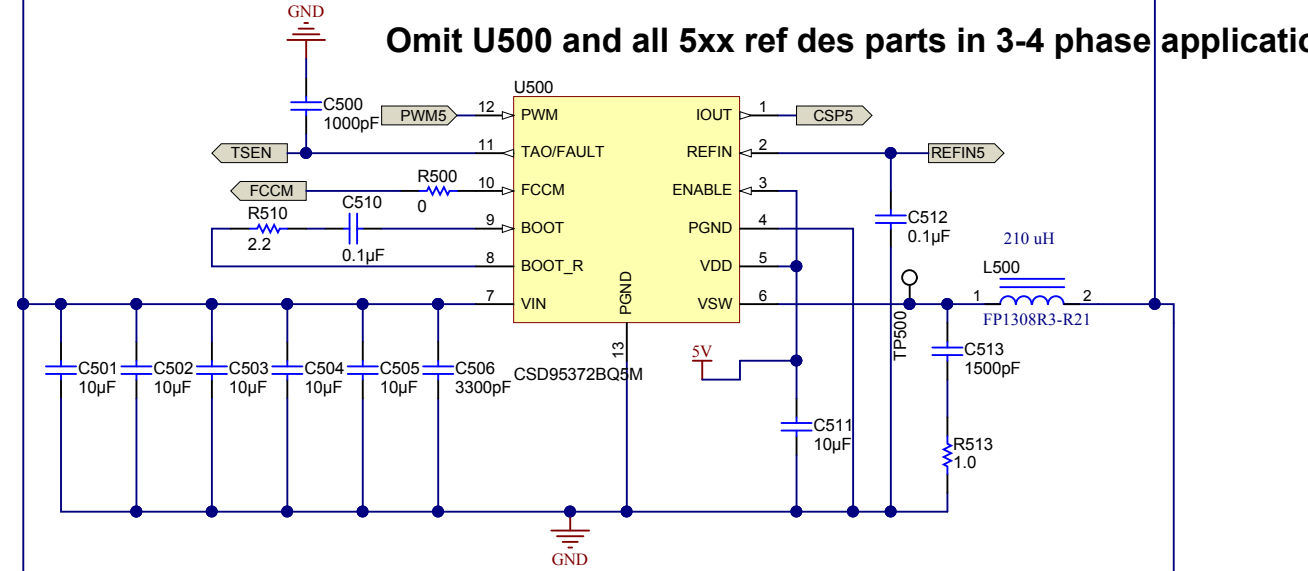
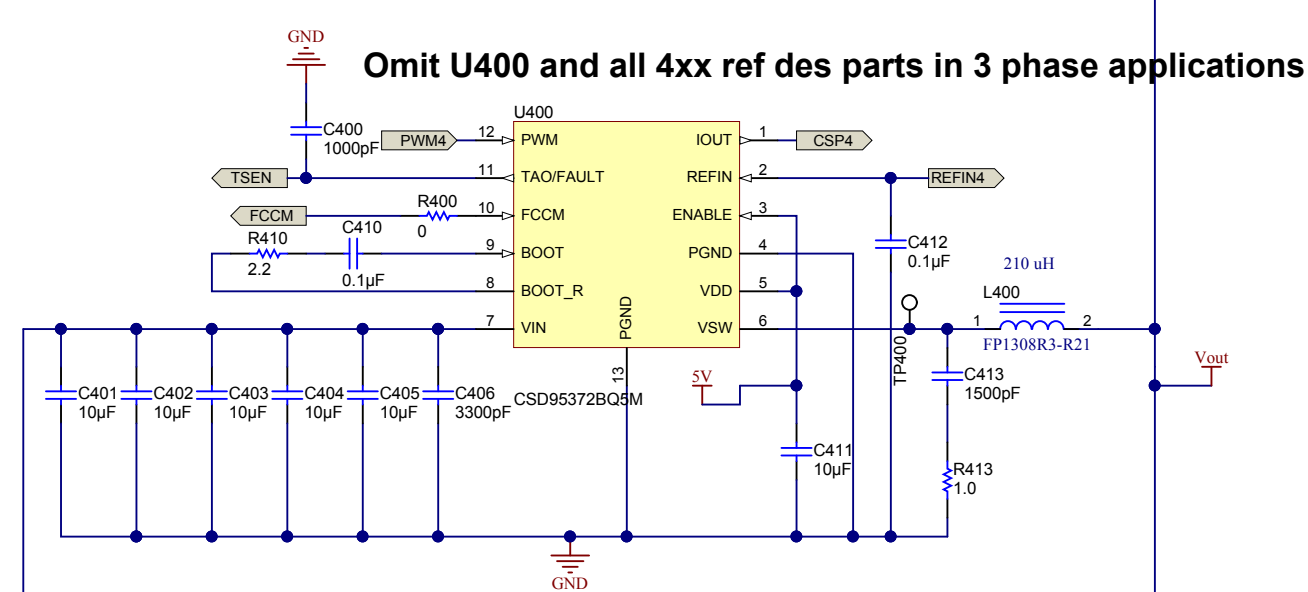
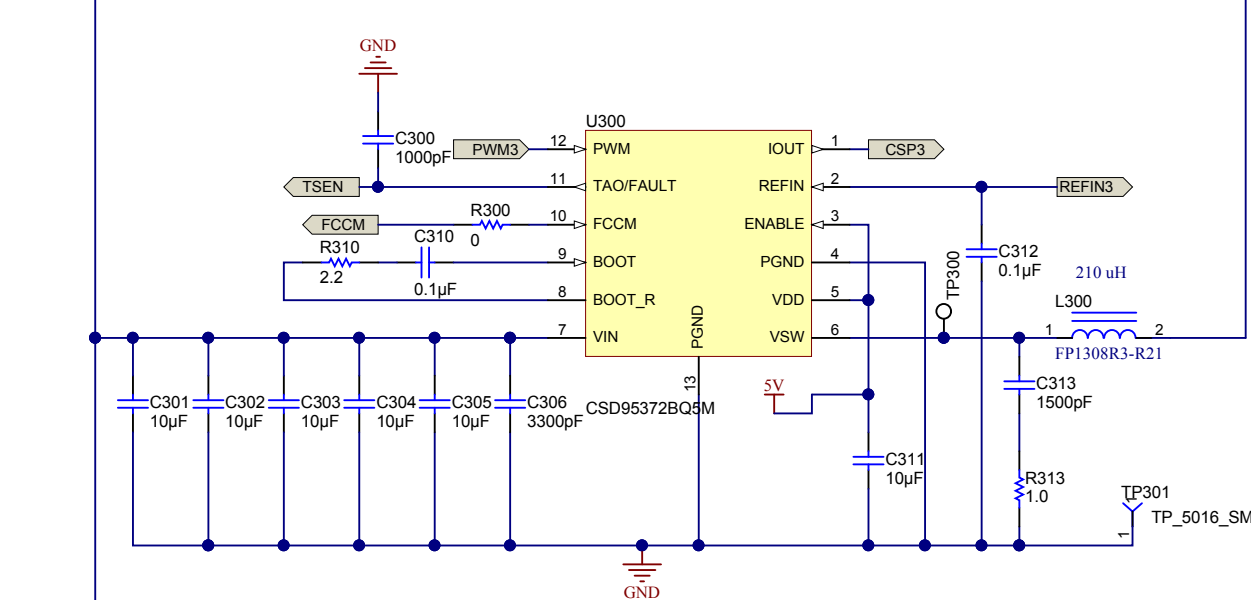
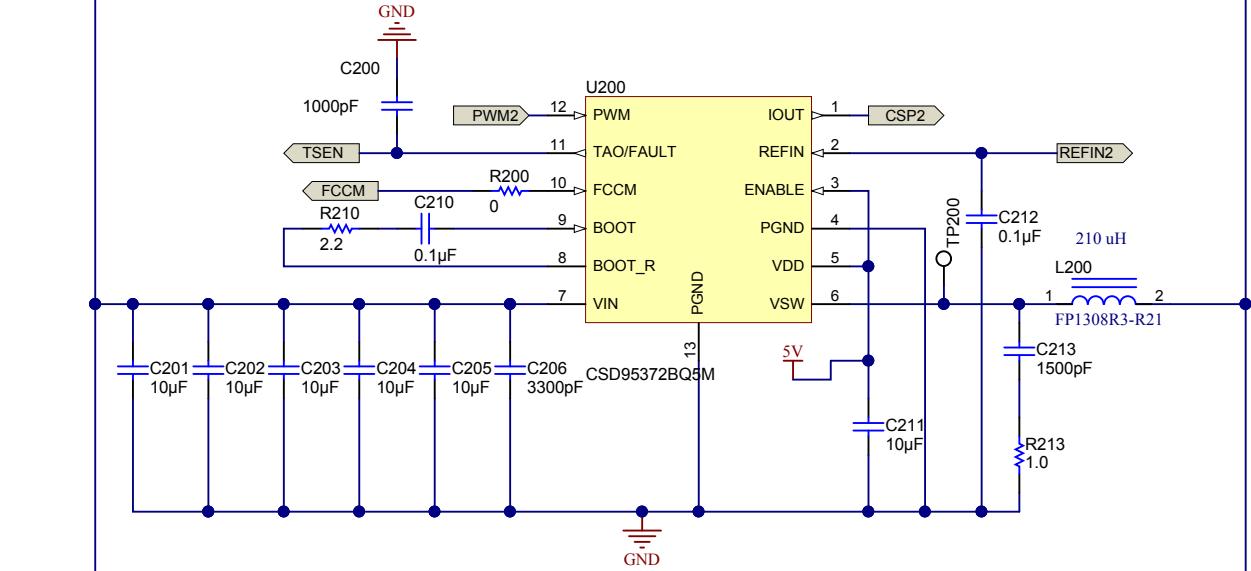
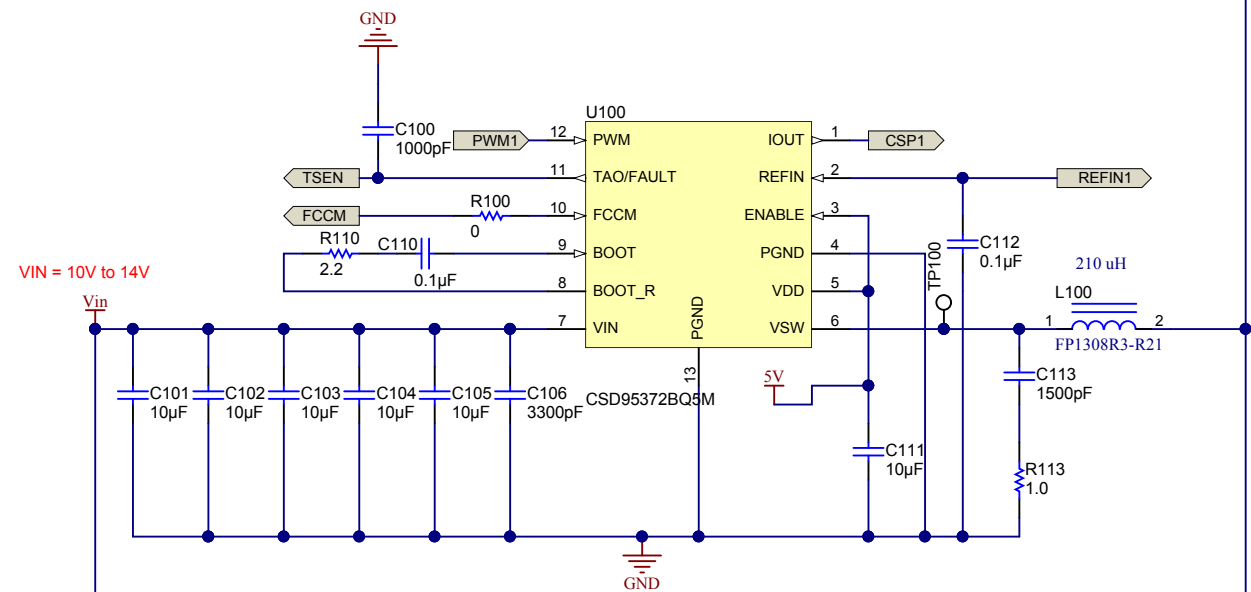


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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/12/2015
TID #: PMP10393	Project Title: TPS53661: 12vin to 600mV 200A	
Number: PMP10393 on PMP9738	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: PMP10393_TPS53661_Control.SchDoc	Size: B
Engineer: Josh Mandelcorn	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





For lower cost versions, U100-U600 become CSD95373BQ5M in same package

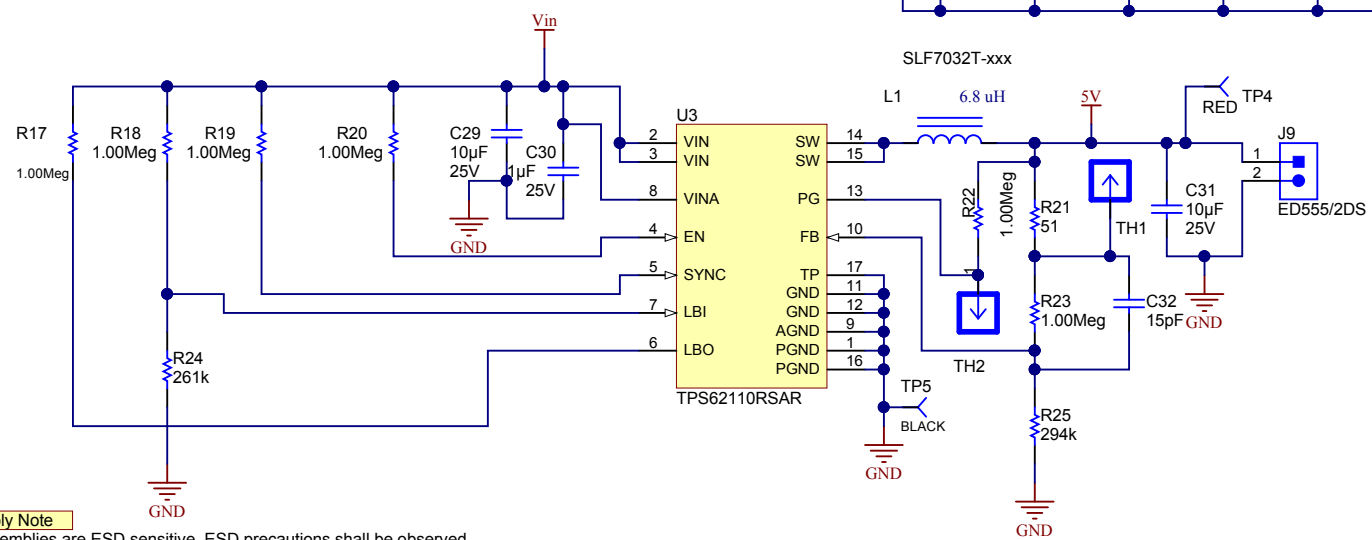
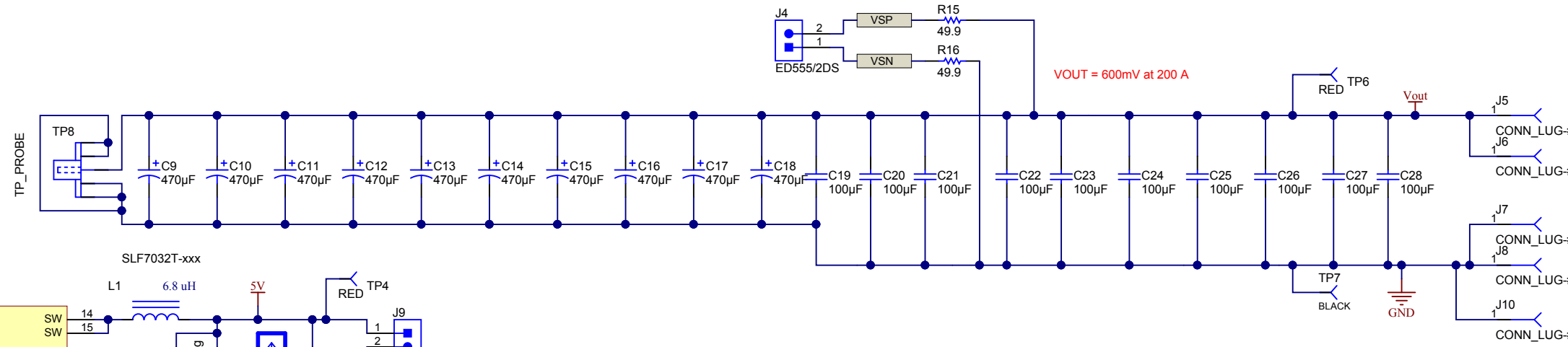
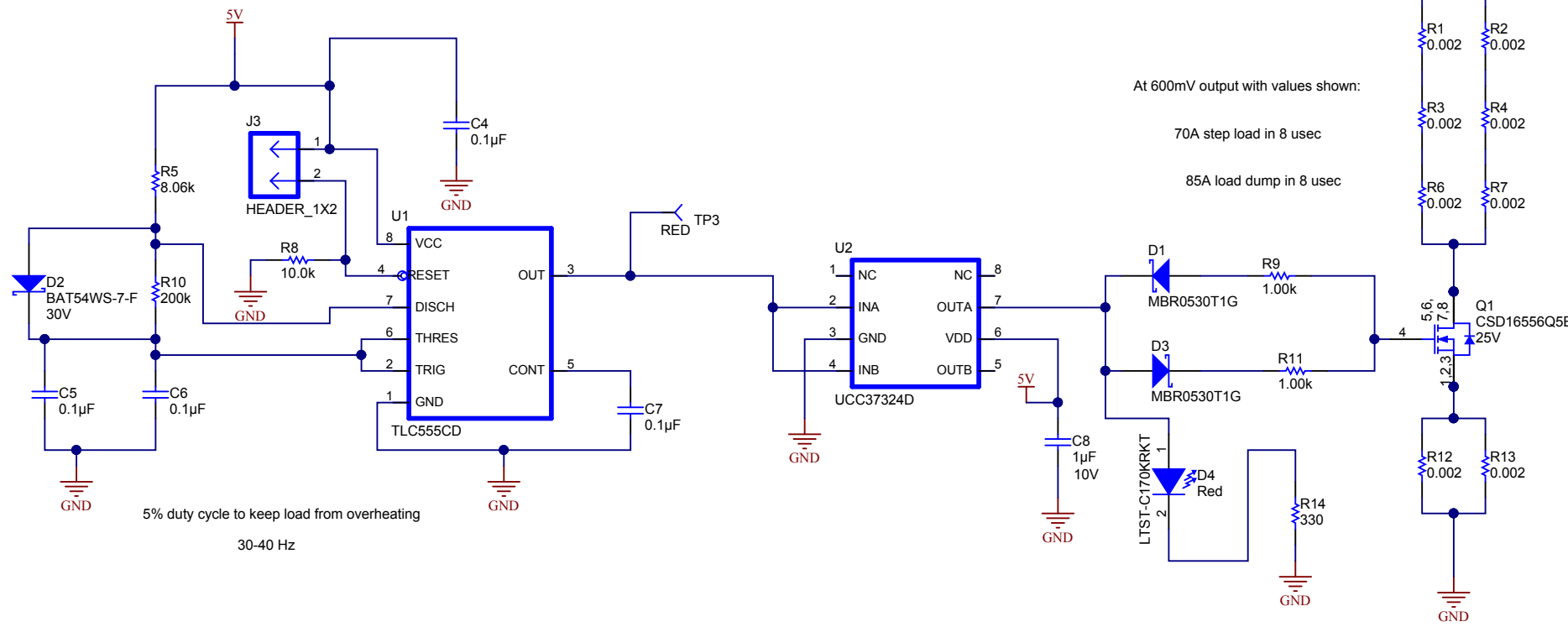
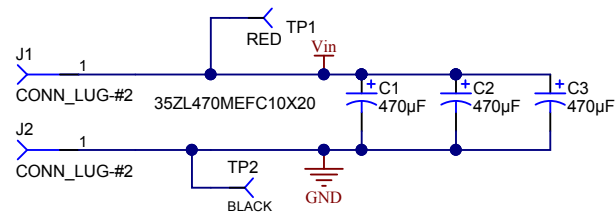
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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/12/2015
TID #: PMP10393	Project Title: TPS53661: 12vin to 600mV 200A	
Number: PMP10393 on PMP9738	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: PMP10393_CSD95372B_PowerTrains.SchDoc	Size: B
Engineer: Josh Mandelcorn	Contact: http://www.ti.com/support	



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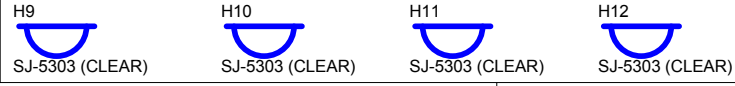
ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

PCB Number: PMP10393 on PCB PMP9738  
PCB Rev: A

**Built on PCB PMP9738A**



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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/12/2015
TID #: PMP10393	Project Title: TPS53661: 12vin to 600mV 200A	
Number: PMP10393 on PCB PMP9738	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: PMP10393_Input_Bias_Output_DynLoad_SchDoc	Size: B
Engineer: Josh Mandelcorn	Contact: http://www.ti.com/support	



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